



CALL FOR PAPERS

INTERNATIONAL WORKSHOP ON INTEGRATED POWER PACKAGING 2025

April 8th – 10th 2025

**University of Alabama
Tuscaloosa, Alabama, USA**

This workshop aims to unite power electronics packaging researchers to advance high-density, high-efficiency power converters. We seek papers tackling challenges in power electronic components and systems, offering solutions for enhanced reliability, manufacturability, and performance at lower costs. Submissions are solicited on all power packaging topics ranging from component-level to system-level.

- **Materials, Semiconductors and Components**
 - Power Semiconductor Devices
 - Packaging Materials
 - High Temperature & High Voltage Dielectrics
 - High-Temperature Capacitors
 - Printed Circuit Boards (PCB)
 - High-Frequency Magnetics
 - Thermal Interface Materials
- **Packaging, manufacturing, and semiconductor integration**
 - Design for Manufacturability, Compatibility with Standards
 - Die attach and wire bonding
 - Innovative packaging strategies
 - Interconnection technologies

- **Reliability, Thermal and Electrical Management**
 - Components to System Reliability
 - Reliability Assessment & Lifetime Prediction
 - Partial Discharge
 - Thermal Management
 - Power Cycling
- **Converter and system integration**
 - Electromagnetic Interference
 - System Integration and Optimization
 - Compact Converter Design Techniques
 - Gate/Base Drivers, Sensors & Protection

IWIPP COMMITTEE

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PSMA Liaison: Brian Narveson

DEADLINES

Abstract Submission: **November 1, 2024**

Notice of Acceptance: December 20, 2024

Final Paper Submission: February 7, 2025

Submission Portal (available Sept. 1, 2024):

<https://epapers.org/iwipp2025/>

